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Abstract

Improved Method and Apparatus for an integrated circuit dicing device

A method for dicing substrates to produce sorted singulated units, comprising the steps of loading (1) said substrates to a rail system (2); delivering said substrates via the rail system to a chuck table arrangement (4) for dicing said substrates; dicing said substrates to produce singulated units held within a predetermined spatial arrangement; flipping said substrates whilst maintaining the predetermined spatial arrangement; delivering the singulated units to a net block assembly (10) to separate and control individual units, and sorting and categorizing (12) the individual units so as to separate them by efficacy.

Figure 1